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Part Number:

0737700100

Status:

Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 72 Circuits

Documents:

3D Model

Drawing (PDF)

Product Specification PS-73780-999 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

UL

LR19980

E29179

General

Product Family

Series

Application

Component Type

MolexKits

Overview

Product Name

UPC

Backplane Connectors

73770

Backplane, Mezzanine

PCB Header

Yes

HDM® Backplane Connector System

HDM®

800755029000

Physical

Circuits (Loaded)

Circuits (maximum)

Color - Resin

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Material - Metal

Material - Plating Mating

Material - Plating Termination

Material - Resin

Net Weight

Number of Columns

Number of Pairs

Number of Rows

Orientation

PC Tail Length

PCB Locator

PCB Retention

PCB Thickness - Recommended

Packaging Type

Pitch - Mating Interface

Pitch - Termination Interface

Plating min - Mating

Plating min - Termination

Polarized to PCB

Stackable

Surface Mount Compatible (SMC)

Temperature Range - Operating

Termination Interface: Style

72

72

Black

200

No

94V-0

No

None

Phosphor Bronze

Gold

Tin-Lead

High Temperature Thermoplastic

13.179/g

12

Open Pin Field

6

Vertical

3.50mm

No

None

1.40mm

Tube

2.00mm

2.00mm

0.762µm

0.381µm

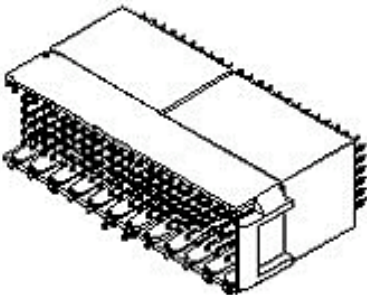
No

Yes

Yes

-55°C to +105°C

Through Hole - Compliant Pin



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

China RoHS

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

Search Parts in this Series

73770 Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	

Electrical

Current - Maximum per Contact	1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	250V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73770-001

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